Product / Package Information

Package	SOIC_N
Body Size	150 mils
Lead Count	8
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	3.64E-02	87.7	877000	51.15	511478
Thermosets	Phenol Resin	Proprietary	1.66E-03	4.0	40000	2.33	23329
Thermosets	Epoxy Resin 1	Proprietary	1.25E-03	3.0	30000	1.75	17496
Thermosets	Epoxy Resin 2	Proprietary	1.45E-03	3.5	35000	2.04	20412
Others	Others	Proprietary	6.23E-04	1.5	15000	0.87	8748
Other inorganic materials	Carbon Black	1333-86-4	1.25E-04	0.3	3000	0.17	1750
Subtotal			4.15 E-02	100.00	1000000	58.32	583214

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	2.34 E-02	97.5	975000	32.88	328762
Copper & its alloys	Iron	7439-89-6	5.64 E-04	2.35	23500	0.79	7924
Copper & its alloys	Zinc	7440-66-6	2.88 E-05	0.12	1200	0.04	405
Copper & its alloys	Phosphorus	7723-14-0	7.21 E-06	0.03	300	0.01	101
Subtotal			2.40 E-02	100.00	1000000	33.72	337192

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	2.43E-04	100.0	1000000	0.34	3406

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	1.37 E-03	100.0	1000000	1.92	19186

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	2.97 E-04	99.00	990000	0.42	4169
Precious Metals	Palladium	7440-05-3	3.00 E-06	1.00	10000	0.004	42
Subtotal			3.00 E-04	100.0	1000000	0.42	4212

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.63 E-03	100.0	1000000	3.69	36925

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	8.70 E-04	77.00	770000	1.22	12216
Other organic materials	Acrylic resin	Proprietary	7.91 E-05	7.00	70000	0.11	1111
Other organic materials	Acrylate	Proprietary	6.22 E-05	5.50	55000	0.09	873
Other organic materials	Polybutadiene derivative	Proprietary	5.09 E-05	4.50	45000	0.07	714
Thermoset	Epoxy resin	Proprietary	2.83 E-05	2.50	25000	0.04	397
Other organic materials	Butadiene Copolymer	Proprietary	1.70 E-05	1.50	15000	0.02	238
Others	Additive	Proprietary	1.70 E-05	1.50	15000	0.02	238
Others	Peroxide	Proprietary	5.65 E-06	0.50	5000	0.008	79
Subtotal			1.13 E-03	100.0	1000000	1.59	15865

	Weight (g)	Percentage (%)	PPM
Package Totals	**7.12 E-02**	**100**	**1000000**

Control ID: MS000506CPKG3626
Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

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